LOW-TEMPERATURE SINTERED SILVER NANOPARTICLE COMPOSITION AND ELECTRONIC ARTICLES FORMED USING THE SAME

Abstract

A silver nanoparticle composition is provided which is possible to be sintered through sintering at a low temperature in a short time and to form silver electro conductive film and wiring which is favorable for adhesion to a substrate and low in resistance, and articles using the same are provided. The silver nanoparticle composition is provided, wherein a main component of a solvent is water, a pH of the composition is within a range of 5.3 to 8.0, a silver nanoparticle included in the composition is protected by an organic acid or a derivative thereof, and the content of the organic acid or the derivative thereof with respect to silver is 2 to 20% by mass.

No figure to accompany the abstract when published